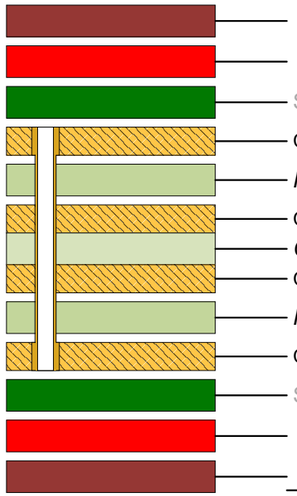
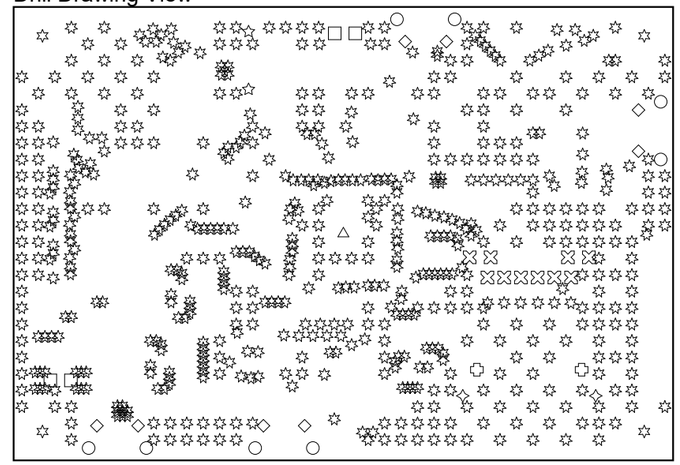
Layer Stack Legend



Material	Layer	Thickness	Dielectric Material	Type	Gerber
	Top Paste			Paste Mask	GTP
	Top Overlay			Legend	GTO
Surface Material	Top Solder	0.010mm	Solder Resist	Solder Mask	GTS
Copper	Top Layer	0.035mm		Signal	GTL
Prepreg		*0.220mm*		*Dielectric*	
Copper	Mid Layer 1	0.035mm		Signal	G1
Core		*0.400mm*		*Dielectric*	
Copper	Mid Layer 2	0.035mm		Signal	G2
Prepreg		*0.220mm*		*Dielectric*	
Copper	Bottom Layer	0.035mm		Signal	GBL
Surface Material	Bottom Solder	0.010mm	Solder Resist	Solder Mask	GBS
	Bottom Overlay			Legend	GBO
	Bottom Paste			Paste Mask	GBP

Total thickness: 1.000mm

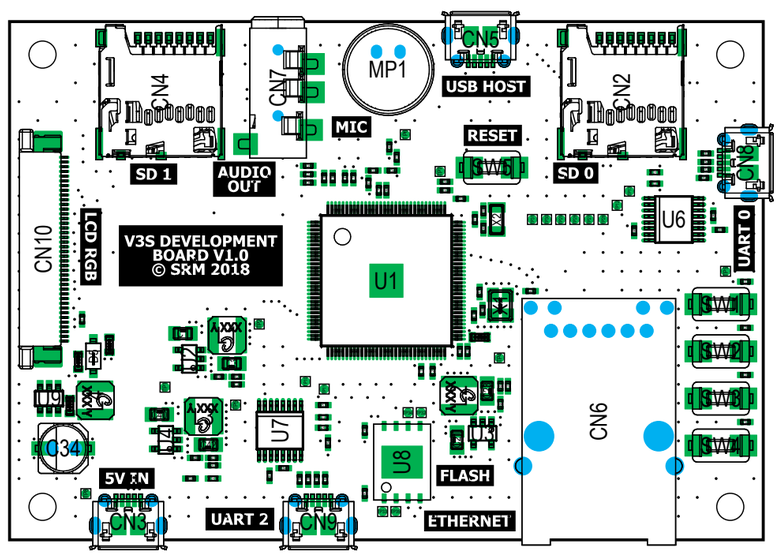
Drill Drawing View

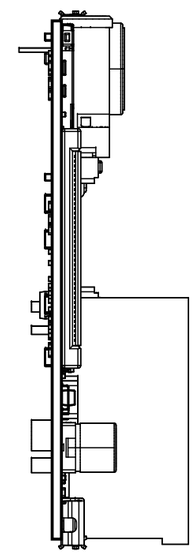


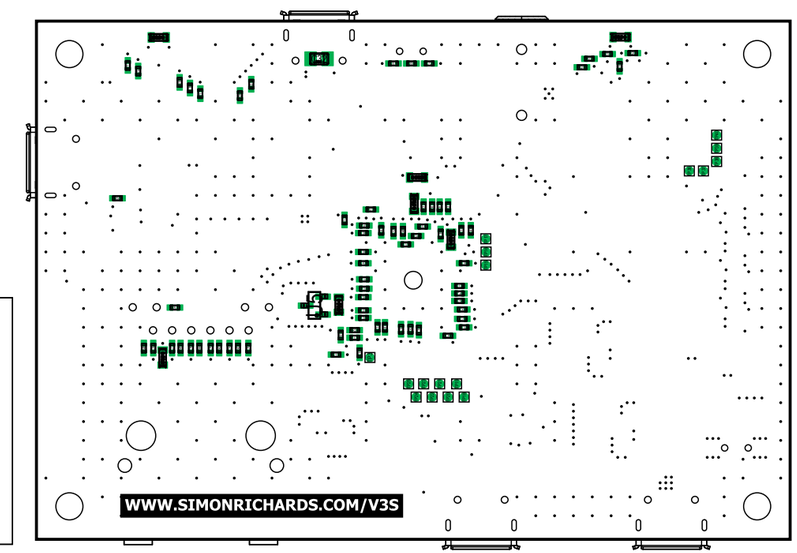
Drill Table

Symbol	Count	Hole Size	Plated	Hole Tolerance
□	4	0.80	Plated	None
○	8	0.60	Plated	None
◇	8	0.85	Plated	None
⊠	10	0.89	Plated	None
✪	2	3.25	Non-Plated	None
✧	2	1.57	Plated	None
☆	2	1.20	Non-Plated	None
☆	4	3.00	Non-Plated	None
☆	616	0.30	Plated	None
△	1	2.00	Plated	None

1. Dimensioning and tolerancing in accordance with ASME Y14.5M.
2. Acceptance of finished printed circuit boards shall be in accordance with IPC-600.
3. Fabrication and inspection shall be according to IPC-6011 and IPC-6012, Class 2.
4. Material:
   A. Copper clad laminate and prepreg shall be glass fiber epoxy (FR4, ER=4.5) and conform to IPC-4101/126.
   B. Copper foil shall be according to IPC-4562, Type E, Grade 3, Class 2.
   C. Dielectric thickness and finished copper weights shall be in accordance with stack-up diagram.
   D. All dielectric materials shall be RoHS compliant and UL recognised.
5. All holes shall be located within 0.008mm of true position. Drilling should be according to IPC-DR-572. See drill table for finished hole sizes and tolerances.
6. All plated holes shall have a minimum average plated thickness of 0.003mm.
7. Mark top and bottom sides with applicable silkscreen artwork. Use white, permanent, non-conductive epoxy ink. Remove silkscreen from solderable land areas.
8. Maximum allowable bow and twist shall be 0.75% (0.07mm max).
9. Solder mask shall be applied to both sides over bare copper.
10. Board outline is shown in *.GKO gerber file.







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			NAME	DATE
UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN INCHES TOLERANCES: FRACTIONAL± ANGULAR: MACH± BEND ± TWO PLACE DECIMAL ± THREE PLACE DECIMAL ±	DRAWN	SRM		10/03/2018
	CHECKED			
	ENG APPR.			
	MFG APPR.			
INTERPRET GEOMETRIC TOLERANCING PER:	Q.A.			
MATERIAL	COMMENTS:			
FINISH				
DO NOT SCALE DRAWING				

NEXT ASSY	USED ON
APPLICATION	

SRM

TITLE

V3S Dev Board V1.0

SIZE	DWG. NO.	
SCALE:	WEIGHT:	SHEET 1 OF 1